

CHIP COIL (CHIP INDUCTORS) LQW2BAS□□□□00L REFERENCE SPECIFICATION

1. Scope

This Reference specification applies to LQW2BAS_00 series, Chip coil (Chip Inductors).

2. Part Numbering

(ex)	LQ	W	2B	A	S	2N8	J	0	0	L
	Product ID	Structure	Dimension (L×W)	Applications and Characteristics	Category	Inductance	Tolerance	Features	Electrode	Packaging L:Taping *B:Bulk

*Bulk packing also available. (A product is put in the plastic bag under the taping conditions.)

3. Rating

- Operating Temperature Range -55°C ~ +125°C
- Storage Temperature Range. -55°C ~ +125°C

Customer Part Number	MURATA Part Number	Inductance		Q (min.)	DC Resistance (Ω max.)	Self Resonant Frequency (MHz min.)	Rated Current (mA)	
		(nH)	Tolerance					
	LQW2BAS2N7J00L	2.7	J : ±5%	80	0.03	15000	910	
	LQW2BAS2N8J00L	2.8			0.06	12200	800	
	LQW2BAS3N0J00L	3.0		65	0.08	5900		
	LQW2BAS5N6J00L	5.6			70	0.03		4500
	LQW2BAS6N0J00L	6.0		50		0.11		5600
	LQW2BAS6N8J00L	6.8			0.14	4800		
	LQW2BAS7N5J00L	7.5		G : ±2% J : ±5%	60	0.12		4400
	LQW2BAS8N2G00L	8.2	50			0.10		4300
	LQW2BAS8N2J00L				12	0.15	4000	
	LQW2BAS10NG00L	15	0.17				3200	
	LQW2BAS10NJ00L				18	0.20	3100	
	LQW2BAS12NG00L	22	55				0.22	2600
	LQW2BAS12NJ00L				24	50		2400
	LQW2BAS15NG00L	27	55				0.25	2580
	LQW2BAS15NJ00L				33	60		0.27
	LQW2BAS18NG00L	36	55				0.29	
	LQW2BAS18NJ00L			39	60	0.31		1700
	LQW2BAS22NG00L	43	60				0.34	1800
	LQW2BAS22NJ00L			47	60	0.31		1700
	LQW2BAS24NG00L	56	60				0.34	1600
	LQW2BAS24NJ00L			68	60	0.38		1500
	LQW2BAS27NG00L	82	65				0.42	1330
	LQW2BAS27NJ00L			91	65	0.48		
	LQW2BAS33NG00L	100	65				0.46	1250
	LQW2BAS33NJ00L							
	LQW2BAS36NG00L							
	LQW2BAS36NJ00L							
	LQW2BAS39NG00L							
	LQW2BAS39NJ00L							
	LQW2BAS43NG00L							
	LQW2BAS43NJ00L							
	LQW2BAS47NG00L							
	LQW2BAS47NJ00L							
	LQW2BAS56NG00L							
	LQW2BAS56NJ00L							
	LQW2BAS68NG00L							
	LQW2BAS68NJ00L							
	LQW2BAS82NG00L							
	LQW2BAS82NJ00L							
	LQW2BAS91NG00L							
	LQW2BAS91NJ00L							
	LQW2BASR10G00L							
	LQW2BASR10J00L							

Customer Part Number	MURATA Part Number	Inductance		Q (min.)	DC Resistance (Ω max.)	Self Resonant Frequency (MHz min.)	Rated Current (mA)	
		(nH)	Tolerance					
	LQW2BASR11G00L	110	G : ±2% J : ±5%	50	0.48	1100	400	
	LQW2BASR11J00L							
	LQW2BASR12G00L	120			0.51			
	LQW2BASR12J00L							
	LQW2BASR15G00L	150			0.56	920		
	LQW2BASR15J00L							
	LQW2BASR18G00L	180		0.64				
	LQW2BASR18J00L							
	LQW2BASR22G00L	220		0.70	820			
	LQW2BASR22J00L							
	LQW2BASR24G00L	240	44	1.00	770	350		
	LQW2BASR24J00L							
	LQW2BASR27G00L	270	48	1.40	650	310		
	LQW2BASR27J00L							
	LQW2BASR33G00L	330	J : ±5%	33	1.50	600	290	
	LQW2BASR33J00L							
	LQW2BASR39J00L	390		23	1.76	300	250	
	LQW2BASR47J00L							
	LQW2BASR56J00L	560		1.90	270	250	190	
	LQW2BASR68J00L							
	LQW2BASR82J00L	820		2.20	230	230	180	
	LQW2BASR82J00L							
	LQW2BAS1R0J00L	1000			23	2.35	230	180
	LQW2BAS1R0J00L				23	2.40	200	170

4. Testing Conditions

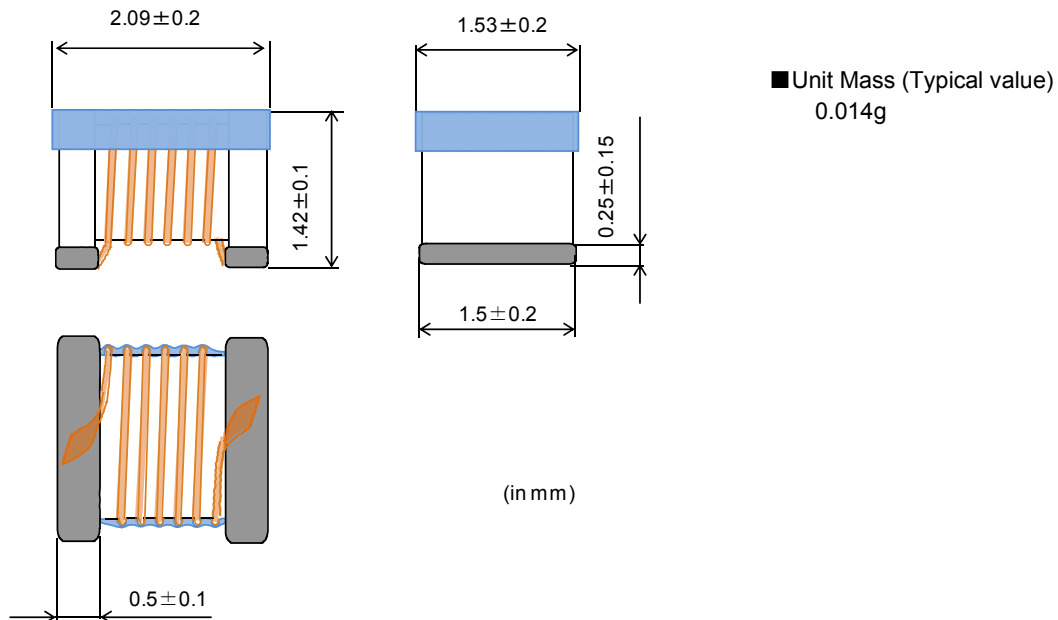
《Unless otherwise specified》

Temperature : Ordinary Temperature / 15°C to 35°C
 Humidity : Ordinary Humidity / 25%(RH) to 85%(RH)

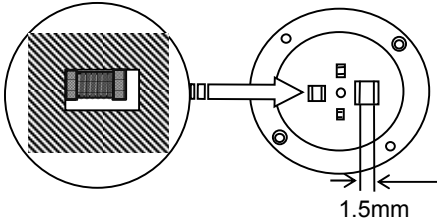
《In case of doubt》

Temperature : 20°C±2°C
 Humidity : 60%(RH) to 70%(RH)
 Atmospheric Pressure : 86kPa to 106 kPa

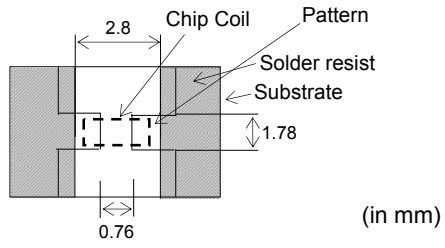
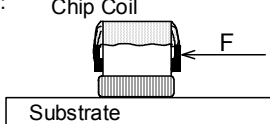
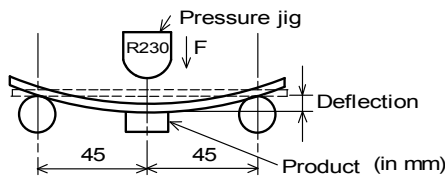
5. Appearance and Dimensions



6. Electrical Performance

No.	Item	Specification	Test Method
6.1	Inductance	Inductance shall meet item 3.	Measuring Equipment : KEYSIGHT 4287A or equivalent Measuring Frequency : <Inductance> 250MHz / 2.7nH~ 39nH 200MHz / 43nH~ 68nH 150MHz / 82nH~ 120nH 100MHz / 150nH~ 390nH 50MHz / 470nH 25MHz / 560nH~1000nH <Q> 1500MHz / 2.7nH~ 3.0nH 1000MHz / 5.6nH~ 8.2nH 500MHz / 10nH~ 100nH 250MHz / 110nH~ 390nH 100MHz / 470nH 50MHz / 560nH~1000nH Measuring Condition : Test signal level / about 0dBm Electrode spaces / 2.0 mm Electrical length / 10.0mm Weight / about 1N~3N
6.2	Q	Q shall meet item 3.	Measuring Fixture : KEYSIGHT 16197A Position coil under test as shown in below and contact coil with each terminal by adding weight.  Measuring Method : See the endnote. <Electrical Performance : Measuring Method of Inductance / Q>
6.3	DC Resistance	DC Resistance shall meet item 3.	Measuring Equipment : Digital multi meter
6.4	Self Resonant Frequency(SRF)	S.R.F shall meet item 3.	Measuring Equipment : KEYSIGHT 8753C or equivalent
6.5	Rated Current	Self temperature rise shall be limited to 40°C max.	The rated current is applied.

7. Mechanical Performance

No.	Item	Specification	Test Method
7.1	Shear Test	Chip coil shall not be damaged after tested as test method.	<p>Substrate : Glass-epoxy substrate</p>  <p>(in mm)</p> <p>Applied Direction : </p> <p>Force : 10N Hold Duration : 5s±1s</p>
7.2	Bending Test		<p>Substrate : Glass-epoxy substrate (100mm×40mm×1.0mm)</p> <p>Speed of Applying Force : 1mm / s Deflection : 3mm Hold Duration : 5s</p>  <p>(in mm)</p>
7.3	Vibration		<p>Oscillation Frequency : 10Hz~2000Hz~10Hz for 15 min</p> <p>Total amplitude 3 mm or Acceleration amplitude 196m/s² whichever is smaller.</p> <p>Time : A period of 2 hours in each of 3 mutually perpendicular directions.(Total 6hours)</p>
7.4	Solderability	The wetting area of the electrode shall be at least 90% covered with new solder coating.	<p>Flux : Ethanol solution of rosin, 25(wt)% Includes activator equivalent to 0.06(wt)% chlorine. (immersed for 5s to 10s)</p> <p>Solder : Sn-3.0Ag-0.5Cu Pre-Heating : 150°C±10°C / 60s to 90s Solder Temperature : 240°C±5°C Immersion Time : 3s±1s</p>
7.5	Resistance to Soldering Heat	Appearance : No damage Inductance Change : within ±5%	<p>Flux : Ethanol solution of rosin, 25(wt)% Includes activator equivalent to 0.06(wt)% chlorine. (immersed for 5s to 10s)</p> <p>Solder : Sn-3.0Ag-0.5Cu Pre-Heating : 150°C±10°C / 60s to 90s Solder Temperature : 270°C±5°C Immersion Time : 10s±1s Then measured after exposure in the room condition for 24h±2h.</p>

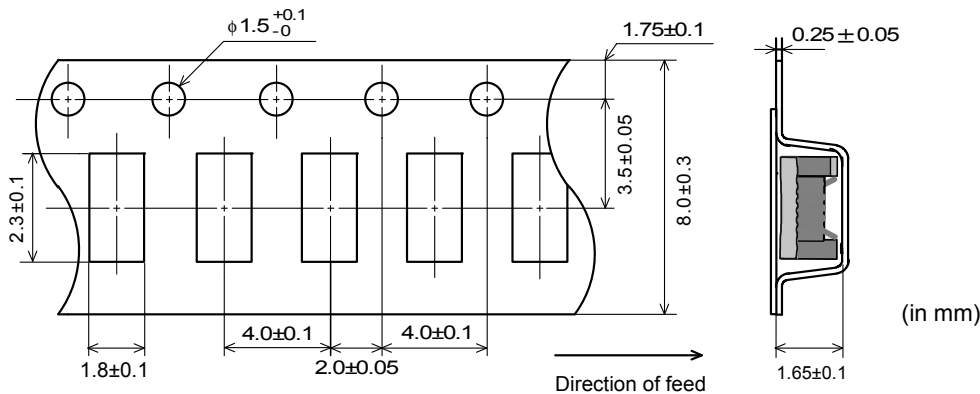
8. Environmental Performance

It shall be soldered on the substrate.

No.	Item	Specification	Test Method
8.1	Heat Resistance	Appearance : No damage Inductance Change : within ±5% Q Change : within ±20%	Temperature : 125°C±2°C Time : 1000h (+48h,0h) Then measured after exposure in the room condition for 24h±2h.
8.2	Cold Resistance		Temperature : -55°C±2°C Time : 1000h (+48h,-0h) Then measured after exposure in the room condition for 24±2 h.
8.3	Humidity		Temperature : 85°C±2°C Humidity : 85%(RH) Time : 1000h (+48h,-0h) Then measured after exposure in the room condition for 24h±2h.
8.4	Temperature Cycle		1 cycle : 1 step : -55°C±2°C / 30min±3 min 2 step : Ordinary temp. / 10min to 15 min 3 step : +125°C±2°C / 30min±3 min 4 step : Ordinary temp. / 30min±3 min Total of 10 cycles Then measured after exposure in the room condition for 24h±2h.

9. Specification of Packaging

9.1 Appearance and Dimensions of plastic tape (8mm-wide, 4mm-pitch)



•Dimension of the Cavity is measured at the bottom side.

9.2 Specification of Taping

- (1) Packing quantity (standard quantity)
2,000 pcs / reel
- (2) Packing Method
Products shall be packed in the each embossed cavity of plastic tape and sealed by cover tape.
- (3) Sprocket hole
Sprocket holes are to the right as the tape is pulled toward the user.
- (4) Spliced point
Plastic tape and Cover tape has no spliced point.
- (5) Missing components number
Missing components number within 0.1 % of the number per reel or 1 pc., whichever is greater, and are not continuous. The specified quantity per reel is kept.

9.3 Pull Strength

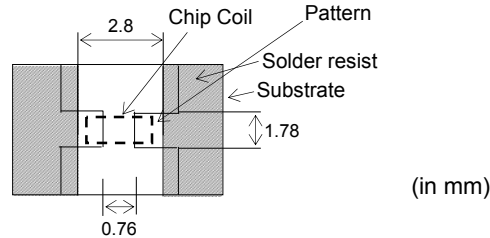
Plastic tape	5N min.
Cover tape	10N min.

11. Notice

Products can only be soldered with reflow.
 This product is designed for solder mounting.
 Please consult us in advance for applying other mounting method such as conductive adhesive.

11.1 Land pattern designing

Recommended land patterns for reflow soldering are as follows:
 These have been designed for Electric characteristics and solderability.
 Please follow the recommended patterns. Otherwise, their performance which includes electrical performance or solderability may be affected, or result to "position shift" in soldering process.

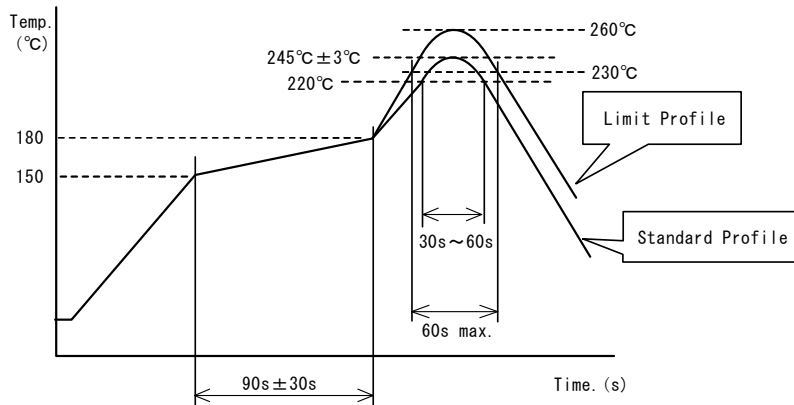


11.2 Flux, Solder

- Use rosin-based flux.
 Includes middle activator equivalent to 0.06(wt)% to 0.1(wt)% Chlorine.
 Don't use highly acidic flux with halide content exceeding 0.2(wt)% (chlorine conversion value).
 Don't use water-soluble flux.
- Use Sn-3.0Ag-0.5Cu solder.
- Standard thickness of solder paste : 100 μ m to 150 μ m.

11.3 Reflow soldering conditions

- Pre-heating should be in such a way that the temperature difference between solder and product surface is limited to 150°C max. Cooling into solvent after soldering also should be in such a way that the temperature difference is limited to 100°C max.
 Insufficient pre-heating may cause cracks on the product, resulting in the deterioration of products quality.
- Standard soldering profile and the limit soldering profile is as follows.
 The excessive limit soldering conditions may cause leaching of the electrode and / or resulting in the deterioration of product quality.
- Reflow soldering profile



	Standard Profile	Limit Profile
Pre-heating	150°C ~ 180°C , 90s ± 30s	
Heating	above 220°C, 30s ~ 60s	above 230°C, 60s max.
Peak temperature	245°C ± 3°C	260°C, 10s
Cycle of reflow	2 times	

11.4 Reworking with soldering iron

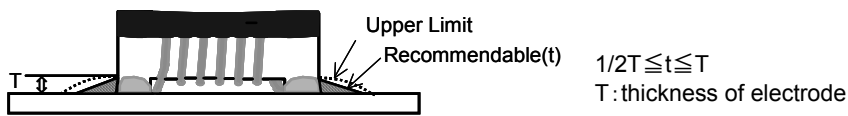
The following conditions must be strictly followed when using a soldering iron.

Pre-heating	150°C, 1 min
Tip temperature	350°C max.
Soldering iron output	80W max.
Tip diameter	φ3mm max.
Soldering time	3(+1,-0)s
Time	2 times

Note: Do not directly touch the products with the tip of the soldering iron in order to prevent the crack on the products due to the thermal shock.

11.5 Solder Volume

- Solder shall be used not to exceed the upper limits as shown below.
- Accordingly increasing the solder volume, the mechanical stress to Chip is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance.

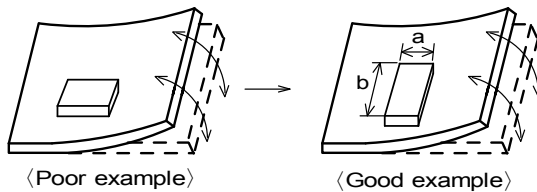


11.6 Product's location

The following shall be considered when designing and laying out P.C.B.'s.

- (1) P.C.B. shall be designed so that products are not subject to the mechanical stress due to warping the board.

[Products direction]



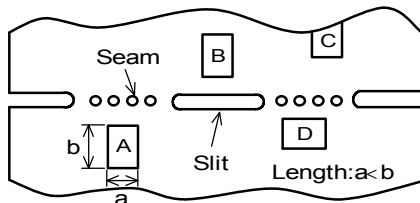
Products shall be located in the sideways direction (Length: a < b) to the mechanical stress.

- (2) Components location on P.C.B. separation.

It is effective to implement the following measures, to reduce stress in separating the board.

It is best to implement all of the following three measures; however, implement as many measures as possible to reduce stress.

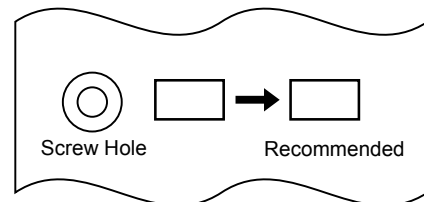
Contents of Measures	Stress Level
(1) Turn the mounting direction of the component parallel to the board separation surface.	A > D *1
(2) Add slits in the board separation part.	A > B
(3) Keep the mounting position of the component away from the board separation surface.	A > C



*1 A > D is valid when stress is added vertically to the perforation as with Hand Separation. If a Cutting Disc is used, stress will be diagonal to the PCB, therefore A > D is invalid.

- (3) Mounting Components Near Screw Holes

When a component is mounted near a screw hole, it may be affected by the board deflection that occurs during the tightening of the screw. Mount the component in a position as far away from the screw holes as possible.



11.7 Cleaning Conditions

Products shall be cleaned on the following conditions.

- (1) Cleaning temperature shall be limited to 60°C max. (40°C max for IPA.)
- (2) Ultrasonic cleaning shall comply with the following conditions with avoiding the resonance phenomenon at the mounted products and P.C.B.
Power : 20 W / l max. Frequency : 28kHz to 40kHz Time : 5 min max.
- (3) Cleaner
 1. Alcohol type cleaner
Isopropyl alcohol (IPA)
 2. Aqueous agent
PINE ALPHA ST-100S
- (4) There shall be no residual flux and residual cleaner after cleaning.
In the case of using aqueous agent, products shall be dried completely after rinse with de-ionized water in order to remove the cleaner.
- (5) Other cleaning Please contact us.

11.8 Resin coating

The inductance value may change due to high cure-stress of resin to be used for coating/molding products.

An open circuit issue may occur by mechanical stress caused by the resin, amount/cured shape of resin, or operating condition etc. Some resin contains some impurities or chloride possible to generate chlorine by hydrolysis under some operating condition may cause corrosion of wire of coil, leading to open circuit.

So, please pay your careful attention when you select resin in case of coating/molding the products with the resin.

Prior to use the coating resin, please make sure no reliability issue is observed by evaluating products mounted on your board.

11.9 Caution for use

- Sharp material such as a pair of tweezers or other material such as bristles of cleaning brush, shall not be touched to the winding portion to prevent the breaking of wire.
- Mechanical shock should not be applied to the products mounted on the board to prevent the breaking of the core.

11.10 Notice of product handling at mounting

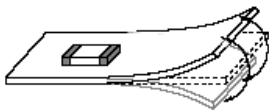
In some mounting machines, when picking up components support pin pushes up the components from the bottom of plastic tape. In this case, please remove the support pin. The support pin may damage the components and break wire.

11.11 Handling of a substrate

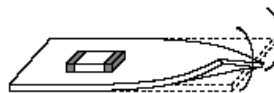
After mounting products on a substrate, do not apply any stress to the product caused by bending or twisting to the substrate when cropping the substrate, inserting and removing a connector from the substrate or tightening screw to the substrate.

Excessive mechanical stress may cause cracking in the product.

Bending



Twisting

**11.13 Storage and Handling Requirements****(1) Storage period**

Use the products within 12 months after delivered.

Solderability should be checked if this period is exceeded.

(2) Storage conditions

- Products should be stored in the warehouse on the following conditions.

Temperature : -10°C to 40°C

Humidity : 15% to 85% relative humidity No rapid change on temperature and humidity

The electrode of the products is coated with solder. Don't keep products in corrosive gases such as sulfur, chlorine gas or acid, or it may cause oxidization of electrode, resulting in poor solderability.

- Products should not be stored on bulk packaging condition to prevent the chipping of the core and the breaking of winding wire caused by the collision between the products.
- Products should be stored on the palette for the prevention of the influence from humidity, dust and so on.
- Products should be stored in the warehouse without heat shock, vibration, direct sunlight and so on.

(3) Handling Condition

Care should be taken when transporting or handling product to avoid excessive vibration or mechanical shock.

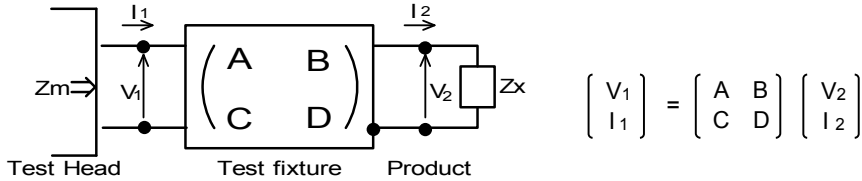
12. Note

- (1) Please make sure that your product has been evaluated in view of your specifications with our product being mounted to your product.
- (2) You are requested not to use our product deviating from the agreed specifications.
- (3) The contents of this reference specification are subject to change without advance notice.
Please approve our product specifications or transact the approval sheet for product specifications before ordering.

< Electrical Performance: Measuring Method of Inductance / Q >

To keep compatibility to other vender's product, Inductance and Q value shall be measured in following method.

(1) Residual elements and stray elements of test fixture can be described by F-parameter shown in following.



(2) The impedance of chip coil Zx and measured value Zm can be described by input/output current/voltage.

$$Z_m = \frac{V_1}{I_1}, \quad Z_x = \frac{V_2}{I_2}$$

(3) Thus, the relation between Zx and Zm is following ;

$$Z_x = \alpha \frac{Z_m - \beta}{1 - Z_m \Gamma} \quad \text{where, } \alpha = D / A = 1$$

$$\beta = B / D = Z_{sm} - (1 - Y_{om} Z_{sm}) Z_{ss}$$

$$\Gamma = C / A = Y_{om}$$

- Zsm : measured impedance of short chip
- Zss : residual impedance of short chip (=equivalent series Inductance X)
- Yom : measured admittance when opening the fixture

Important : X : Zss shall be defined as correction value to fit nominal inductance of other venders' products.
Please input X value instead of equivalent series Inductance (Short L) on test equipment calibration.

(4) Lx and Qx shall be calculated with the following equation.

$$L_x = \frac{\text{Im}(Z_x)}{2\pi f}, \quad Q_x = \frac{\text{Im}(Z_x)}{\text{Re}(Z_x)} \quad f : \text{Measuring frequency}$$

Inductance and Q value shall be measured after this calibration setting.
In addition, Q value should be measured under our standard calibration setting of residual impedance, 0.771nH.

Chart. equivalent series Inductance to fit nominal inductance of other vendors' products.

MURATA Part Number	Inductance	
	X [nH] equivalent series Inductance	Measuring Frequency
LQW2BAS2N7_00	0.121	250
LQW2BAS2N8_00	0.171	250
LQW2BAS3N0_00	0.131	250
LQW2BAS5N6_00	-0.009	250
LQW2BAS6N0_00	0.031	250
LQW2BAS6N8_00	0.301	250
LQW2BAS7N5_00	-0.299	250
LQW2BAS8N2_00	0.271	250
LQW2BAS10N_00	-0.229	250
LQW2BAS12N_00	0.371	250
LQW2BAS15N_00	0.051	250
LQW2BAS18N_00	-0.029	250
LQW2BAS22N_00	0.491	250
LQW2BAS24N_00	-0.389	250
LQW2BAS27N_00	0.931	250
LQW2BAS33N_00	0.481	250
LQW2BAS36N_00	0.531	250
LQW2BAS39N_00	0.771	250
LQW2BAS43N_00	-0.689	200
LQW2BAS47N_00	1.091	200
LQW2BAS56N_00	0.331	200
LQW2BAS68N_00	0.811	200
LQW2BAS82N_00	-0.839	150
LQW2BAS91N_00	-1.339	150
LQW2BASR10_00	0.171	150
LQW2BASR11_00	1.371	150
LQW2BASR12_00	-1.629	150
LQW2BASR15_00	-0.029	100
LQW2BASR18_00	4.071	100
LQW2BASR22_00	0.771	100
LQW2BASR24_00	3.071	100
LQW2BASR27_00	-1.429	100
LQW2BASR33_00	4.071	100
LQW2BASR39_00	0.971	100
LQW2BASR47_00	-8.829	50
LQW2BASR56_00	-8.229	25
LQW2BASR68_00	-2.229	25
LQW2BASR82_00	-8.029	25
LQW2BAS1R0_00	-6.329	25